

Laser Applications

Bearbeitet von

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1. Auflage 2004. Buch. xviii, 495 S.

ISBN 978 3 540 00105 8

Format (B x L): 19,3 x 27 cm

Gewicht: 1580 g

[Weitere Fachgebiete > Physik, Astronomie > Elektrodynamik, Optik > Quantenoptik,
Nichtlineare Optik, Laserphysik](#)

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GROUP VIII: Advanced Materials and Technologies

VOLUME 1

Laser Physics and Applications

SUBVOLUME C

Laser Applications

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